

TENTATIVE

CM450TJ-24NF

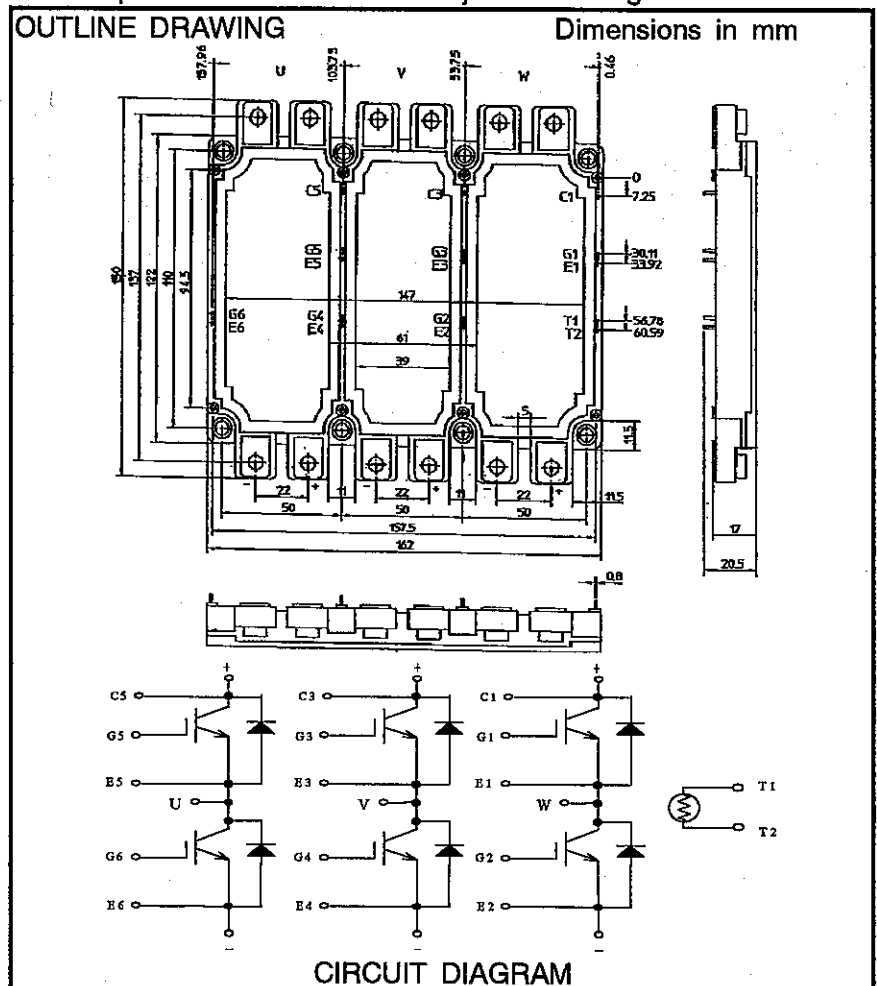
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Apr.	M.Yamamoto July 31.'01			M.Yamamoto Mar.14.'03

HIGH POWER SWITCHING USE

Notice : This is not a final specification. Some parametric limits are subject to change.

CM450TJ-24NF

- I_C 450A
- V_{CES} 1200V
- Insulated Type
- 6-elements in a pack



APPLICATION

General purpose inverters & Servo controls, etc

ABSOLUTE MAXIMUM RATINGS ($T_j = 25\text{ }^\circ\text{C}$)

Symbol	Item	Conditions	Ratings	Units
V_{CES}	Collector-emitter voltage	G-E Short	1200	V
V_{GES}	Gate-emitter voltage	C-E Short	± 20	V
I_C	Collector current	DC, $T_c' = 96\text{ }^\circ\text{C}^*1$	450	A
I_{CM}		Pulse ②	900	
I_E ①	Emitter current		450	A
I_{EM} ①		Pulse ②	900	
P_C ③	Maximum collector dissipation	$T_c' = 25\text{ }^\circ\text{C}$	3040	W
T_j	Junction temperature		$-40 \sim +150$	$^\circ\text{C}$
T_{stg}	Storage temperature		$-40 \sim +125$	$^\circ\text{C}$
Viso	Isolation voltage	Main terminal to base plate, AC 1 min.	2500	V
-	Torque strength	Main terminal M6	$3.5 \sim 4.5$	N·m
-	Torque strength	Mounting holes M5	$2.5 \sim 3.5$	N·m
-	Weight	Typical value	1100	g

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Units			
I_{CES}	Collector cutoff current	$V_{CE}=V_{CES}, V_{GE}=0V$	—	—	2	mA			
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C=45mA, V_{CE}=10V$	6	7	8	V	C		
I_{GES}	Gate leakage current	$V_{GE}=V_{GES}, V_{CE}=0V$	—	—	0.5	μA	A		
$V_{CE(sat)}$	Collector to emitter saturation voltage	$T_j = 25^\circ\text{C}$ $I_C = 450A$	—	2.0**	2.6**	V			
		$T_j = 125^\circ\text{C}$ $V_{GE} = 15V$	—	2.2**	—				
C_{ies}	Input capacitance	$V_{CE}=10V$	—	—	70	nF	B		
C_{oes}	Output capacitance	$V_{GE}=0V$	—	—	8.1		B		
C_{res}	Reverse transfer capacitance		—	—	1.5		B		
Q_G	Total gate charge	$V_{CC}=600V, I_C=450A, V_{GE}=15V$	—	2400	—	nC	A		
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600V, I_C=450A$	—	—	500	ns	B D		
t_r	Turn-on rise time	$V_{GE1}=V_{GE2}=15V$	—	—	150		B D		
$t_{d(off)}$	Turn-off delay time	$R_G=0.7\Omega$, Inductive load switching operation	—	—	600		B		
t_f	Turn-off fall time		—	—	300		B		
t_{rr} ①	Reverse recovery time		$I_E=450A$	—	—		250	ns	B D
Q_{rr} ①	Reverse recovery charge			—	15		—	μC	B D
V_{EC} ①	Emitter-collector voltage	$I_E=450A, V_{GE}=0V$	—	—	3.2**	V			
$R_{th(j-c)Q}$	Thermal resistance*	IGBT part	—	—	0.041	$^\circ\text{C/W}$	B		
$R_{th(j-c)R}$		FWDi part	—	—	0.048		B		
$R_{th(c-f)}$	Contact thermal resistance	Case to fin, Thermal compound Applied (1/6module)	—	0.048 ²	—				
R_G	External gate resistance		0.7	—	7	Ω	B D		

** : without package drop voltage

*1: T_c measured point is just under the chips.

If you use this value, $R_{th(f-a)}$ should be measured just under the chips.

*2: Typical value is measured by using Shin-etsu Silicone "G-746".

Thermistors part

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
R_{TH}	Resistance	$T_C=25^\circ\text{C}$	—	5	—	$k\Omega$
B	B Constant	Resistance at $25^\circ\text{C}, 50^\circ\text{C}$ ⑤	—	3375	—	K

① $I_E, V_{EC}, t_{rr}, Q_{rr}$ & die/dt represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

② Pulse width and repetition rate should be such that the device junction temp. (T_j) dose not exceed T_{jmax} rating.

③ Junction temperature (T_j) should not increase beyond 150°C .

④ Pulse width and repetition rate should be such as to cause negligible temperature rise.

⑤ $B = (\ln R_1 - \ln R_2) / (1/T_1 - 1/T_2)$ R_1 : Resistance at $T_1(K)$ R_2 : Resistance at $T_2(K)$